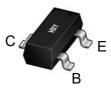


Features

- High breakdown voltage
- Low collector-emitter saturation voltage

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBTA42	SOT-23	1D	3000

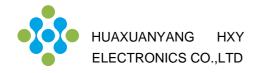


SOT-23



Maxmim Ratings (Ta=25 unless otherwise noted)

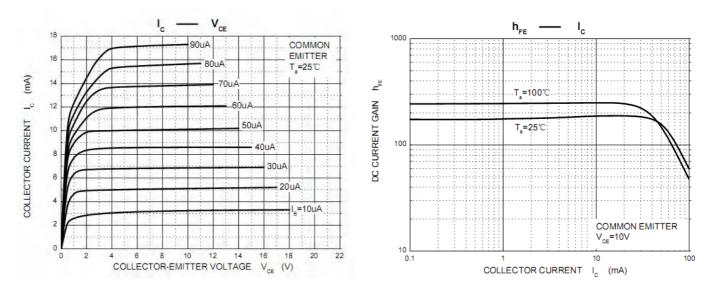
Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	300	V
Collector-Emitter Voltage	V _{CEO}	300	V
Emitter-Base Voltage	V _{EBO}	5	V
Collector Current	Ι _c	300	mA
Collector Power Dissipation	P _c	350	mW
Thermal Resistance From Junction To Ambient	R _{ØJA}	357	°C/W
Junction Temperature	Т _ј	150	°C
Storage Temperature	T _{stg}	-55~+150	°C



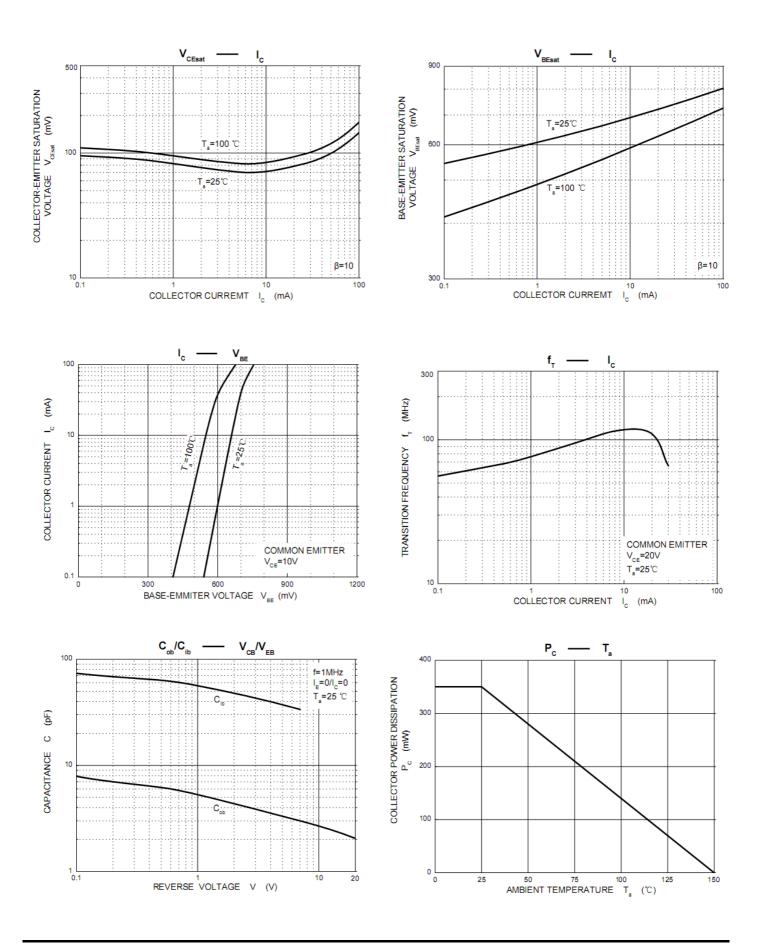
Parameter	Symbol	Test conditions	Min	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C = 100μΑ,I _E =0	300		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = 1mA, I _B =0	300		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = 100μΑ, I _C =0	5		V
Collector cut-off current	I _{CBO}	V _{CB} =200V, I _E =0		0.25	μA
Emitter cut-off current	I _{EBO}	V _{EB} = 5V, I _C =0		0.1	μA
	h _{FE(1)}	V _{CE} = 10V, I _C = 1mA	60		
DC current gain	h _{FE(2)}	V _{CE} = 10V, I _C =10mA	100	200	
	h _{FE(3)}	V _{CE} =10V, I _C =30mA	60		
Collector-emitter saturation voltage	V _{CE} (sat)	I _C =20mA, I _B = 2mA		0.2	V
Base-emitter saturation voltage	V _{BE} (sat)	I _C = 20mA, I _B =2mA		0.9	V
Transition frequency	f⊤	V _{CE} = 20V, I _C = 10mA, f=30MHz	50		MHz

Electrcal Charcteristics (T a=25 unless otherwise specified)

Typical Characteristics

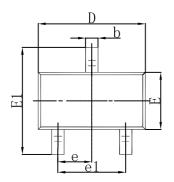


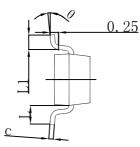


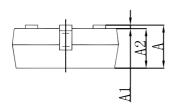




SOT-23 Package Outline Dimensions

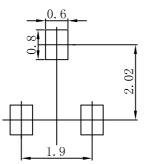






Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
Α	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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